

HIP6019

Advanced Dual PWM and **Dual Linear Power Control**

March 1998

Features

- · Provides 4 Regulated Voltages
 - Microprocessor Core, I/O, Clock Chip and GTL Bus
- Drives N-Channel MOSFETs
- · Operates from +5V and +12V Inputs
- · Simple Single-Loop Control Designs
 - Voltage-Mode PWM Control
- · Fast Transient Response
 - High-Bandwidth Error Amplifiers
 - Full 0% to 100% Duty Ratios
- Excellent Output Voltage Regulation
 - Core PWM Output: ±1% Over Temperature
 - I/O PWM Output: ±2% Over Temperature
 - Other Outputs: ±2.5% Over Temperature
- TTL-Compatible 5-Bit Digital-to-Analog Core Output Voltage Selection
 - Wide Range 1.8V_{DC} to 3.5V_{DC}
 - 0.1V Steps from 2.1V_{DC} to 3.5V_{DC}
 - 0.05V Steps from 1.8V_{DC} to 2.05V_{DC}
- · Power-Good Output Voltage Monitor
- · Microprocessor Core Voltage Protection Against Shorted MOSFET
- · Over-Voltage and Over-Current Fault Monitors
 - Does Not Require Extra Current Sensing Element, Uses MOSFET's r_{DS(ON)}
- · Small Converter Size
 - Constant Frequency Operation
 - 200kHz Free-Running Oscillator; Programmable from 50kHz to 1MHz

Applications

- Full Motherboard Power Regulation for Computers
- Low-Voltage Distributed Power Supplies

Ordering Information

PART NUMBER	TEMP. (°C)	PACKAGE	PKG. NO.		
HIP6019CB	0 to 70	28 Ld SOIC	M28.3		
HIP6019EVAL1	Evaluation Board				

Description

Pinout

The HIP6019 provides the power control and protection for four output voltages in high-performance microprocessor and computer applications. The IC integrates two PWM controllers, a linear regulator and a linear controller as well as the monitoring and protection functions into a single 28 lead SOIC package. One PWM controller regulates the microprocessor core voltage with a synchronous-rectified buck converter, while the second PWM controller supplies the computer's 3.3V power with a standard buck converter. The linear controller regulates power for the GTL bus and the linear regulator provides power for the clock driver circuits.

The HIP6019 includes an Intel-compatible, TTL 5-input digital-to-analog converter (DAC) that adjusts the core PWM output voltage from $2.1V_{DC}$ to $3.5V_{DC}$ in 0.1V increments and from $1.8V_{DC}$ to $2.05V_{DC}$ in 0.05V steps. The precision reference and voltage-mode control provide ±1% static regulation. The second PWM controller is user-adjustable for output levels between 3.0V and 3.5V with ±2% accuracy. The adjustable linear regulator uses an internal pass device to provide 2.5V ±2.5%. The adjustable linear controller drives an external N-Channel MOSFET to provide 1.5V ±2.5%.

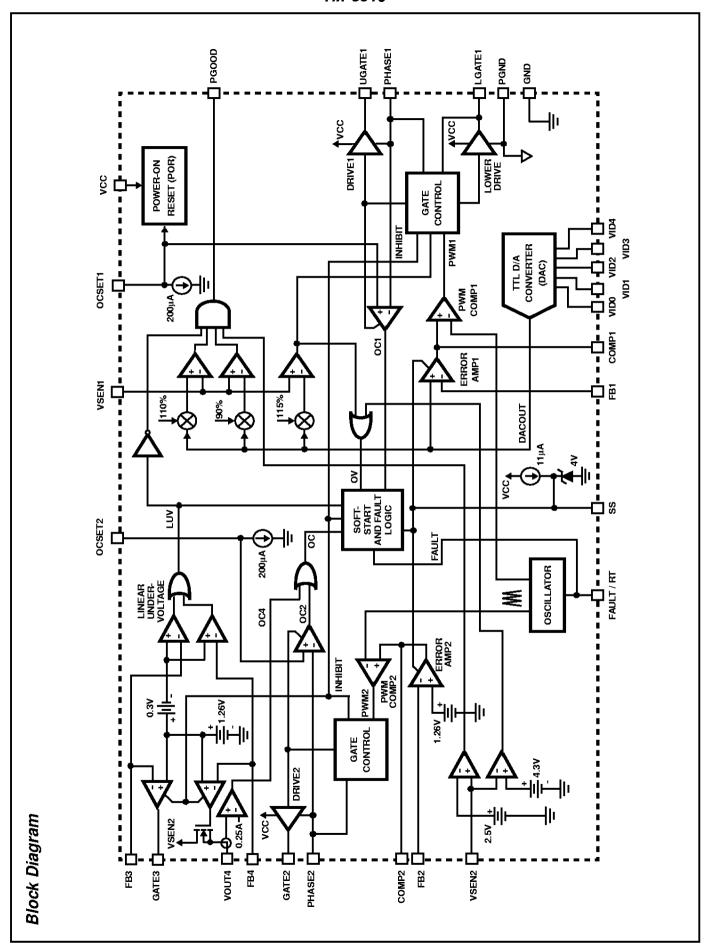
The HIP6019 monitors all the output voltages. A single Power Good signal is issued when the core is within $\pm 10\%$ of the DAC setting and the other levels are above their undervoltage levels. Additional built-in over-voltage protection for the core output uses the lower MOSFET to prevent output voltages above 115% of the DAC setting. The PWM controller's over-current functions monitor the output current by sensing the voltage drop across the upper MOSFET's r_{DS(ON)}, eliminating the need for a current sensing resistor.

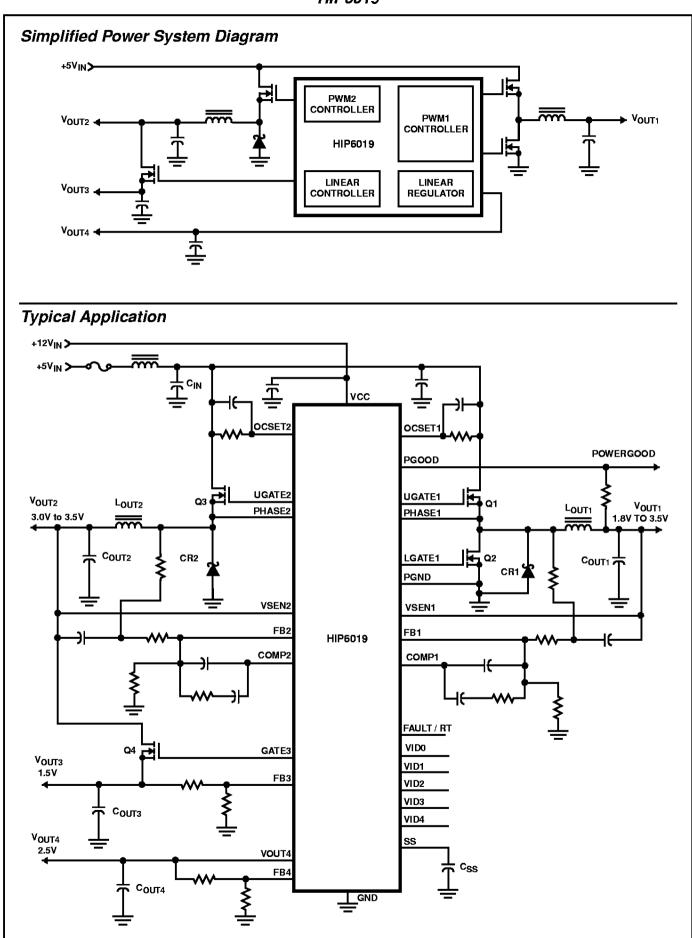
HIP6019 (SOIC) TOP VIEW UGATE2 1 28 VCC PHASE2 2 27 UGATE1 VID4 26 PHASE1 VID3 25 LGATE1 24 PGND VID2 23 OCSET1 VID1 6 VIDO 22 VSEN1 21 FB1 PGOOD 8 OCSET2 9 20 COMP1 FB2 10 19 FB3 COMP2 11 18 GATE3 SS 17 GND

FAULT/RT 13

FB4 14

16 VOUT4 15 VSEN2





HIP6019

Absolute Maximum Ratings

Recommended Operating Conditions

Supply Voltage, V _{CC}	+12V ±10%
Ambient Temperature Range	0°C to 70°C
Junction Temperature Range	°C to 125°C

Thermal Information

Thermal Resistance (Typical, Note 1) θ_{JA}	(°C/W)
	60
SOIC Package (with 3 in ² of copper)	50
Maximum Junction Temperature (Plastic Package)	150°C
Maximum Storage Temperature Range65°C to	150°C
Maximum Lead Temperature (Soldering 10s)	300°C
(SOIC - Lead Tips Only)	

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTE

1. θ_{JA} is measured with the component mounted on an evaluation PC board in free air.

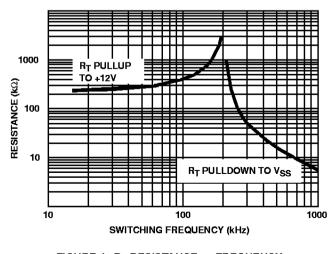
Electrical Specifications Recommended Operating Conditions, Unless Otherwise Noted. Refer to Figures 1, 2 and 3

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
VCC SUPPLY CURRENT		•				
Nominal Supply	lcc	UGATE1, GATE2, GATE3, LGATE1, and VOUT4 Open	-	10	-	mA
POWER-ON RESET		•				
Rising VCC Threshold		V _{OCSET} = 4.5V	8.6	-	10.4	٧
Falling VCC Threshold		V _{OCSET} = 4.5V	8.2	-	10.2	٧
Rising V _{OCSET1} Threshold			-	1.25	-	٧
OSCILLATOR		•				
Free Running Frequency		RT = OPEN	185	200	215	kHz
Total Variation		6kΩ < RT to GND < 200kΩ	-15	-	+15	%
Ramp Amplitude	ΔV _{OSC}	RT = Open	-	1.9	-	V _{P-P}
REFERENCE AND DAC						
DAC(VID0-VID4) Input Low Voltage			-	-	0.8	٧
DAC(VID0-VID4) Input High Voltage			2.0	-	-	٧
DACOUT Voltage Accuracy			-1.0	-	+1.0	%
Reference Voltage (Pin FB2, FB3, and FB4)			1.240	1.265	1.290	٧
LINEAR REGULATOR		•				
Regulation		10mA < I _{VOUT4} < 150mA	-2.5	-	2.5	%
Under-Voltage Level	FB4 _{UV}	FB4 Rising	-	75	87	%
Under-Voltage Hysteresis			-	6	-	%
Over-Current Protection			180	230	-	mA
Over-Current Protection During Start-Up		C _{SS} Voltage < 4V	560	700	-	mA
LINEAR CONTROLLER						
Regulation		VSEN3 = GATE3	-2.5	-	2.5	%
Under-Voltage Level	FB3 _{UV}	FB3 Rising	-	75	87	%
Under-Voltage Hysteresis			-	6	-	%

Electrical Specifications Recommended Operating Conditions, Unless Otherwise Noted. Refer to Figures 1, 2 and 3 **(Continued)**

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
PWM CONTROLLER ERROR AMPLIFI	ERS					
DC Gain			-	88	-	dB
Gain-Bandwidth Product	GBWP		-	15	-	MHz
Slew Rate	SR	COMP = 10pF	-	6	-	V/µs
PWM CONTROLLER GATE DRIVERS						
Drive1 (and 2) Source	lugate	VCC = 12V, V _{UGATE1} (or V _{GATE2}) = 6V	-	1	-	Α
Drive1 (and 2) Sink	R _{UGATE}	V _{GATE-PHASE} = 1V	-	1.7	3.5	Ω
Lower Gate Source	ILGATE	VCC = 12V, V _{LGATE} = 1V	-	1	-	Α
Lower Gate Sink	R _{LGATE}	V _{GATE} = 1V	-	1.4	3.0	Ω
PROTECTION						
V _{OUT1} Over-Voltage Trip		VSEN1 Rising	112	115	118	%
V _{OUT2} Over-Voltage Trip		VSEN2 Rising	4.1	4.3	4.5	٧
VSEN2 Input Resistance			-	70	-	kΩ
FAULT Sourcing Current	lovp	V _{FAULT/RT} = 10.0V	10	14	1	mA
OCSET1(and 2) Current Source	l _{OCSET}	V _{OCSET} = 4.5V _{DC}	170	200	230	μΑ
Soft-Start Current	I _{SS}		-	11	-	μΑ
Chip Shutdown Soft-Start Threshold			-	-	1.0	٧
POWER GOOD						
V _{OUT1} Upper Threshold		VSEN1 Rising	108	-	110	%
V _{OUT1} Under-Voltage		VSEN1 Rising	92	-	94	%
V _{OUT1} Hysteresis		Upper/Lower Threshold	-	2	-	%
V _{OUT2} Under-Voltage		VSEN2 Rising	2.45	2.55	2.65	٧
V _{OUT2} Under-Voltage Hysteresis			-	100	-	mV
PGOOD Voltage Low	V _{PGOOD}	I _{PGOOD} = -4mA	-	-	0.5	٧

Typical Performance Curves



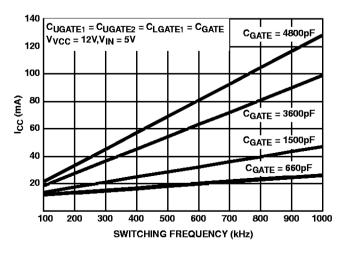


FIGURE 4. R_T RESISTANCE vs FREQUENCY

FIGURE 5. BIAS SUPPLY CURRENT vs FREQUENCY

Functional Pin Description

VSEN1, VSEN2 (Pins 22 and 15)

These pins are connected to the PWM converters' output voltages. The PGOOD and OVP comparator circuits use these signals to report output voltage status and for overvoltage protection. VSEN2 provides the input power to the integrated linear regulator.

OCSET1, OCSET2 (Pins 23 and 9)

Connect a resistor (R_{OCSET}) from this pin to the drain of the respective upper MOSFET. R_{OCSET} , an internal 200 μ A current source (I_{OCSET}), and the upper MOSFET on-resistance ($I_{DS(ON)}$) set the converter over-current (OC) trip point according to the following equation:

$$I_{PEAK} = \frac{I_{OCSET} \times R_{OCSET}}{I_{DS(ON)}}$$

An over-current trip cycles the soft-start function. Sustaining an over-current for 2 soft-start intervals shuts down the controller.

Additionally, OCSET1 is an output for the inverted FAULT signal (FAULT). If a fault condition causes FAULT to go high, OCSET1 will be simultaneously pulled to ground though an internal MOS device (typical $r_{DS(ON)} = 100\Omega$).

SS (Pin 12)

Connect a capacitor from this pin to ground. This capacitor, along with an internal 11µA current source, sets the soft-start interval of the converter.

Pulling this pin low (typically below 1.0V) with an open drain signal will shutdown the IC.

VID0, VID1, VID2, VID3, VID4 (Pins 7, 6, 5, 4 and 3)

VID0-4 are the input pins to the 5-bit DAC. The states of these five pins program the internal voltage reference (DACOUT). The level of DACOUT sets the core converter output voltage (V_{OUT1}). It also sets the core PGOOD and OVP thresholds.

COMP1, COMP2, and FB1, FB2 (Pins 20, 11, 21, and 10)

COMP1, 2 and FB1, 2 are the available external pins of the PWM error amplifiers. Both the FB pins are the inverting input of the error amplifiers. Similarly, the COMP pins are the error amplifier outputs. These pins are used to compensate the voltage-control feedback loops of the PWM converters.

GND (Pin 17)

Signal ground for the IC. All voltage levels are measured with respect to this pin.

PGOOD (Pin 8)

PGOOD is an open collector output used to indicate the status of the PWM converter output voltages. This pin is pulled low when the core output is not within $\pm 10\%$ of the DACOUT reference voltage, or when any of the other outputs are below their under-voltage thresholds.

The PGOOD output is open for VID codes that inhibit operation. See Table 1.

PHASE1, PHASE2 (Pins 26 and 2)

Connect the PHASE pins to the respective PWM converter's upper MOSFET source. These pins are used to monitor the voltage drop across the upper MOSFETs for over-current protection.

UGATE1, UGATE2 (Pins 27 and 1)

Connect UGATE pins to the respective PWM converter's upper MOSFET gate. These pins provide the gate drive for the upper MOSFETs.

PGND (Pin 24)

This is the power ground connection. Tie the synchronous PWM converter's lower MOSFET source to this pin.

LGATE1 (Pin 25)

Connect LGATE1 to the synchronous PWM converter's lower MOSFET gate. This pin provides the gate drive for the lower MOSFET.

VCC (Pin 28)

Provide a 12V bias supply for the IC to this pin. This pin also provides the gate bias charge for all the MOSFETs controlled by the IC.

FAULT/RT (Pin 13)

This pin provides oscillator switching frequency adjustment. By placing a resistor (R_T) from this pin to GND, the nominal 200kHz switching frequency is increased according to the following equation:

$$Fs \approx 200 \, kHz + \frac{5 \times 10^6}{R_T(k\Omega)} \qquad (R_T \text{ to GND})$$

Conversely, connecting a pull-up resistor (R_T) from this pin to VCC reduces the switching frequency according to the following equation:

$$Fs \approx 200 kHz - \frac{4 \times 10^7}{R_T(k\Omega)} \hspace{1cm} (R_T \text{ to 12V})$$

Nominally, this pin voltage is 1.26V, but is pulled to VCC in the event of an over-voltage or over-current condition.

GATE3 (Pin 18)

Connect this pin to the gate of an external MOSFET. This pin provides the drive for the linear controllers pass transistor.

FB3 (Pin 19)

Connect this pin to a resistor divider to set the linear controller output.

VOUT4 (Pin 16)

Output of the linear regulator. Supplies current up to 230mA.

FB4 (Pin 14)

Connect this pin to a resistor divider to set the linear regulator output.

Description

Operation

The HIP6019 monitors and precisely controls 4 output voltage levels (Refer to Figures 1, 2, and 3). It is designed for microprocessor computer applications with 5V power and 12V bias input from a PS2 or ATX power supply. The IC has 2 PWM controllers, a linear controller, and a linear regulator. The first PWM controller (PWM1) is designed to regulate the microprocessor core voltage (VOUT1). PWM1 controller drives 2 MOSFETs (Q1 and Q2) in a synchronous-rectified buck converter configuration and regulates the core voltage to a level programmed by the 5-bit digital-to-analog converter (DAC). The second PWM controller (PWM2) is designed to regulate the I/O voltage (VOLT2). PWM2 controller drives a MOSFET (Q3) in a standard buck converter configuration and regulates the I/O voltage to a resistor programmable level between 3.0 and 3.5V_{DC}. An integrated linear regulator supplies the 2.5V clock generator power (VOLITA). The linear controller drives an external MOSFET (Q4) to supply the GTL bus power (VOLIT3).

Initialization

The HIP6019 automatically initializes upon receipt of input power. Special sequencing of the input supplies is not necessary. The Power-On Reset (POR) function continually monitors the input supply voltages. The POR monitors the bias voltage (+12V_{IN}) at the VCC pin and the 5V input voltage (+5V_{IN}) at the OCSET1 pin. The normal level on OCSET1 is equal to +5V_{IN} less a fixed voltage drop (see over-current protection). The POR function initiates soft-start operation after both input supply voltages exceed their POR thresholds.

Soft-Start

The POR function initiates the soft-start sequence. Initially, the voltage on the SS pin rapidly increases to approximately 1V (this minimizes the soft-start interval). Then an internal $11\mu A$ current source charges an external capacitor (C_{SS}) on the SS pin to 4V. The PWM error amplifier reference inputs (+ terminal) and outputs (COMP1 and COMP2 pins) are clamped to a level proportional to the SS pin voltage. As the SS pin voltage ramps from 1V to 4V, the output clamp allows generation of PHASE pulses of increasing width that charge the output capacitor(s). After this initial stage, the reference input clamp slows the output voltage rate-of-rise and provides a smooth transition to the final set voltage. Additionally, both linear regulator's reference inputs are clamped to a voltage proportional to the SS pin voltage. This method provides a rapid and controlled output voltage rise.

Figure 6 shows the soft-start sequence for the typical application. At T0 the SS voltage rapidly increases to approximately 1V. At T1, the SS pin and error amplifier output voltage reach the valley of the oscillator's triangle wave. The oscillator's triangular waveform is compared to the clamped error amplifier output voltage. As the SS pin voltage increases, the pulsewidth on the PHASE pin increases. The interval of increasing pulse-width continues until each output reaches sufficient voltage to transfer control to the input reference clamp. If we con-

sider the 3.3V output (V_{OUT2}) in Figure 6, this time occurs at T2. During the interval between T2 and T3, the error amplifier reference ramps to the final value and the converter regulates the output to a voltage proportional to the SS pin voltage. At T3 the input clamp voltage exceeds the reference voltage and the output voltage is in regulation.

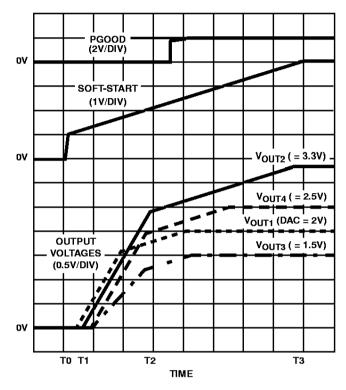


FIGURE 6. SOFT-START INTERVAL

The remaining outputs are also programmed to follow the SS pin voltage. Each linear output (V_{OUT3} and V_{OUT4}) initially follows the 3.3V output (V_{OUT2}). When each output reaches sufficient voltage the input reference clamp slows the rate of output voltage rise. The PGOOD signal toggles 'high' when all output voltage levels have exceeded their under-voltage levels. See the Soft-Start Interval section under Applications Guidelines for a procedure to determine the soft-start interval.

Fault Protection

All four outputs are monitored and protected against extreme overload. A sustained overload on any linear regulator output or an over-voltage on the PWM outputs disables all converters and drives the FAULT/RT pin to VCC.

Figure 7 shows a simplified schematic of the fault logic. An over-voltage detected on either VSEN1 or VSEN2 immediately sets the fault latch. A sequence of three over-current fault signals also sets the fault latch. A comparator indicates when C_{SS} is fully charged (UP signal), such that an undervoltage event on either linear output (FB3 or FB4) is ignored until after the soft-start interval (approximately T3 in Figure 6). At start-up, this allows V_{OUT3} and V_{OUT4} to slew up over increased time intervals, without generating a fault. Cycling the bias input voltage (+12 V_{IN} on the VCC pin) off then on resets the counter and the fault latch.

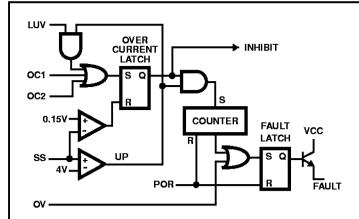


FIGURE 7. FAULT LOGIC - SIMPLIFIED SCHEMATIC

Over-Voltage Protection

During operation, a short on the upper MOSFET (Q1) causes V_{OUT1} to increase. When the output exceeds the over-voltage threshold of 115% of DACOUT, the over-voltage comparator trips to set the fault latch and turns Q2 on as required in order to regulate V_{OUT1} to 1.15 x DACOUT. This blows the input fuse and reduces V_{OUT1} . The fault latch raises the FAULT/RT pin close to VCC potential.

A separate over-voltage circuit provides protection during the initial application of power. For voltages on the VCC pin below the power-on reset (and above \sim 4V), V_{OUT1} is monitored for voltages exceeding 1.26V. Should VSEN1 exceed this level, the lower MOSFET (Q2) is driven on, as needed to regulate V_{OUT1} to 1.26V.

Over-Current Protection

All outputs are protected against excessive over-currents. Both PWM controllers use the upper MOSFET's on-resistance, r_{DS(ON)} to monitor the current for protection against shorted outputs. The linear regulator monitors the current of the integrated power device and signals an over-current condition for currents in excess of 230mA. Additionally, both the linear regulator and the linear controller monitor FB3 and FB4 for under-voltage to protect against excessive currents.

Figures 8 and 9 illustrate the over-current protection with an overload on OUT2. The overload is applied at T0 and the current increases through the output inductor (LOLIT2). At time T1, the OVER-CURRENT2 comparator trips when the voltage across Q3 (ID · rDS(ON)) exceeds the level programmed by ROCSET. This inhibits all outputs, discharges the soft-start capacitor (CSS) with a 11µA current sink, and increments the counter. CSS recharges at T2 and initiates a soft-start cycle with the error amplifiers clamped by soft-start. With OUT2 still overloaded, the inductor current increases to trip the overcurrent comparator. Again, this inhibits all outputs, but the soft-start voltage continues increasing to 4V before discharging. The counter increments to 2. The soft-start cycle repeats at T3 and trips the over-current comparator. The SS pin voltage increases to 4V at T4 and the counter increments to 3. This sets the fault latch to disable the converter. The fault is reported on the FAULT/RT pin.

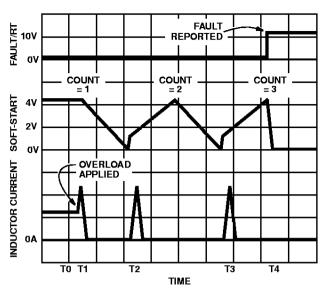


FIGURE 8. OVER-CURRENT OPERATION

The PWM1 controller and the linear regulator operate in the same way as PWM2 to over-current faults. Additionally, the linear regulator and linear controller monitor the feedback pins for an under-voltage. Should excessive currents cause FB3 or FB4 to fall below the linear under-voltage threshold, the LUV signal sets the over-current latch if C_{SS} is fully charged. Blanking the LUV signal during the C_{SS} charge interval allows the linear outputs to build above the under-voltage threshold during normal start-up. Cycling the bias input power off then on resets the counter and the fault latch.

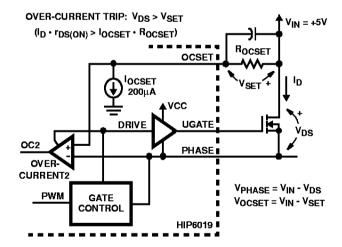


FIGURE 9. OVER-CURRENT DETECTION

Resistors (Rocsett and Rocsett) program the over-current trip levels for each PWM converter. As shown in Figure 9, the internal 200 μ A current sink develops a voltage across Rocset (Vset) that is referenced to Vin. The DRIVE signal enables the over-current comparator (OVER-CURRENT1 or OVER-CURRENT2). When the voltage across the upper MOSFET (VDS) exceeds Vset, the over-current comparator trips to set the over-current latch. Both Vset and VDS are referenced to Vin and a small capacitor across Rocset helps Vocset track the variations of Vin due to MOSFET

switching. The over-current function will trip at a peak inductor current (IPEAK) determined by:

$$I_{PEAK} = \frac{I_{OCSET} \times R_{OCSET}}{I_{DS(ON)}}$$

The OC trip point varies with MOSFET's temperature. To avoid over-current tripping in the normal operating load range, determine the ROCSET resistor from the equation above with:

- The maximum r_{DS(ON)} at the highest junction temperature.
- 2. The minimum IOCSET from the specification table.
- Determine I_{PEAK} for I_{PEAK} > I_{OUT}(MAX) + (ΔI)/2, where ΔI is the output inductor ripple current.

For an equation for the output inductor ripple current see the section under component guidelines titled 'Output Inductor Selection'.

OUT1 Voltage Program

The output voltage of the PWM1 converter is programmed to discrete levels between $1.8V_{DC}$ and $3.5V_{DC}.$ This output is designed to supply the microprocessor core voltage. The voltage identification (VID) pins program an internal voltage reference (DACOUT) through a TTL-compatible 5-bit digital-to-analog converter. The level of DACOUT also sets the PGOOD and OVP thresholds. Table 1 specifies the DACOUT voltage for the different combinations of connections on the VID pins. The VID pins can be left open for a logic 1 input, because they are internally pulled up to +5V by a $10\mu A$ current source. Changing the VID inputs during operation is not recommended. The sudden change in the resulting reference voltage could toggle the PGOOD signal and exercise the over-voltage protection. All VID pin combinations resulting in an INHIBIT disable the IC and the open-collector at the PGOOD pin.

Application Guidelines

Soft-Start Interval

Initially, the soft-start function clamps the error amplifiers' output of the PWM converters. After the output voltage increases to approximately 80% of the set value, the reference input of the error amplifier is clamped to a voltage proportional to the SS pin voltage. The resulting output voltage sequence is shown in Figure 6.

The soft-start function controls the output voltage rate of rise to limit the current surge at start-up. The soft-start interval is programmed by the soft-start capacitor, C_{SS}. Programming a faster soft-start interval increases the peak surge current. The peak surge current occurs during the initial output voltage rise to 80% of the set value.

Shutdown

Neither PWM output switches until the soft-start voltage (V_{SS}) exceeds the oscillator's valley voltage. Additionally, the reference on each linear's amplifier is clamped to the soft-start voltage. Holding the SS pin low (with an open drain or collector signal) turns off all four regulators.

The VID codes resulting in an INHIBIT as shown in Table 1 also shut down the IC.

TABLE 1. VOUT1 VOLTAGE PROGRAM

	NOMINAL				
VID4	VID3	VID2	VID1	VIDO	OUT1 VOLTAGE DACOUT
0	1	Х	Х	Х	INHIBIT
0	0	1	1	1	INHIBIT
0	0	1	1	0	INHIBIT
0	0	1	0	1	1.80
0	0	1	0	0	1.85
0	0	0	1	1	1.90
0	0	0	1	0	1.95
0	0	0	0	1	2.00
0	0	0	0	0	2.05
1	1	1	1	1	INHIBIT
1	1	1	1	0	2.1
1	1	1	0	1	2.2
1	1	1	0	0	2.3
1	1	0	1	1	2.4
1	1	0	1	0	2.5
1	1	0	0	1	2.6
1	1	0	0	0	2.7
1	0	1	1	1	2.8
1	0	1	1	0	2.9
1	0	1	0	1	3.0
1	0	1	0	0	3.1
1	0	0	1	1	3.2
1	0	0	1	0	3.3
1	0	0	0	1	3.4
1	0	0	0	0	3.5

NOTE: 0 = connected to GND or V_{SS}, 1 = open or connected to 5V through pull-up resistors, X = don't care

Layout Considerations

MOSFETs switch very fast and efficiently. The speed with which the current transitions from one device to another causes voltage spikes across the interconnecting impedances and parasitic circuit elements. The voltage spikes can degrade efficiency, radiate noise into the circuit, and lead to device over-voltage stress. Careful component layout and printed circuit design minimizes the voltage spikes in the converter. Consider, as an example, the turnoff transition of the upper MOSFET. Prior to turnoff, the upper MOSFET was carrying the full load current. During the turnoff, current stops flowing in the upper MOSFET and is picked up by the lower MOSFET or Schottky diode. Any inductance in the switched current path generates a large voltage spike during the switching interval. Careful component selection, tight layout of the critical components, and short, wide circuit traces minimize the magnitude of voltage spikes. Contact Harris for evaluation board drawings of the component placement and printed circuit board.